

ABSTRACT OF THE DISCLOSURE

A chip on photosensitive device package structure is provided. The package mainly comprises a photosensitive device, a transparent plate and a chip. The photosensitive device has an illumination area and a non-illumination area. The 5 transparent plate has a first surface and a corresponding second surface. The transparent plate is set over the photosensitive device with the first surface covering both the illumination area and the non-illumination area. The chip is set on the second surface of the transparent plate above the non-illumination area of the photosensitive device.